IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss.

Features

- Optimized for Very Low V_{CEsat}
- Low Switching Loss Reduces System Power Dissipation
- 5 µs Short-Circuit Capability
- These are Pb-Free Devices

Typical Applications

- Solar Inverters
- Uninterruptible Power Supples (UPS)
- Motor Drives

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	600	V
Collector current @ Tc = 25°C @ Tc = 100°C	l _c	100 50	A
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	200	Α
Short–circuit withstand time V_{GE} = 15 V, V_{CE} = 300 V, $T_{J} \le +150^{\circ}C$	t _{SC}	5	μS
Gate-emitter voltage Transient Gate-Emitter Voltage	V_{GE}	±20 ±30	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P_{D}	223 89	W
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

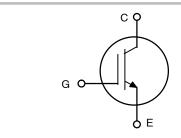
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

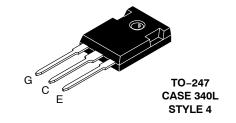


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50 A, 600 V V_{CEsat} = 1.50 V





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTG50N60FWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

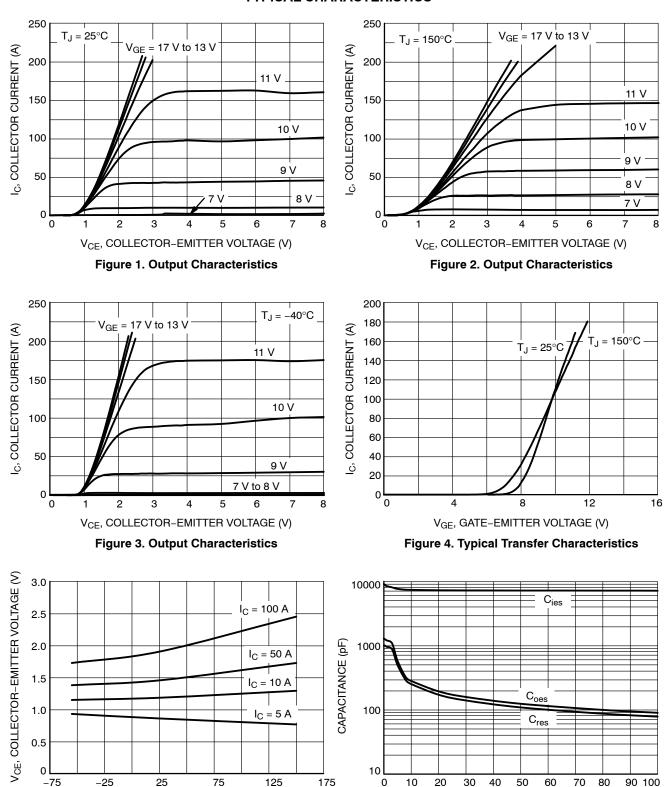
Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.56	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC						
Collector-emitter breakdown voltage, gate-emitter short-circuited	$V_{GE} = 0 \text{ V, I}_{C} = 500 \mu\text{A}$	V _{(BR)CES}	600	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 50 A V _{GE} = 15 V, I _C = 50 A, T _J = 150°C	V _{CEsat}	1.25 -	1.45 1.7	1.7 -	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 350 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 600 V V _{GE} = 0 V, V _{CE} = 600 V, T _J = 150°C	I _{CES}	- -	- -	0.5 2	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V , V _{CE} = 0 V	I _{GES}	-	_	200	nA
DYNAMIC CHARACTERISTIC	•	•				
Input capacitance		C _{ies}	-	7300	_	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	195	_	
Reverse transfer capacitance	7	C _{res}	-	170	_	
Gate charge total		Q_g	-	310	_	nC
Gate to emitter charge	V _{CE} = 480 V, I _C = 50 A, V _{GE} = 15 V	Q _{ge}	-	60	_	
Gate to collector charge	7	Q _{gc}	-	150	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD	-		-	-	5
Turn-on delay time		t _{d(on)}	-	117	-	ns
Rise time	7	t _r	-	43	-	
Turn-off delay time	_ Тյ = 25°C	t _{d(off)}	-	285	_	
Fall time	$V_{CC} = 400 \text{ V}, I_C = 50 \text{ A}$ $R_0 = 10 \Omega$	t _f	-	105	-	
Turn-on switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{ V*}$	E _{on}	-	1.1	-	mJ
Turn-off switching loss	7	E _{off}	-	1.2	-	
Total switching loss	7	E _{ts}	-	2.3	-	
Turn-on delay time		t _{d(on)}	-	112	-	ns
Rise time	7	t _r	-	45	-	
Turn-off delay time	T _J = 150°C	t _{d(off)}	-	300	-	
Fall time	$V_{CC} = 400 \text{ V}, I_{C} = 50 \text{ A}$	t _f	-	214	-	
Turn-on switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 \text{ V} / 15 \text{ V*}$	E _{on}	-	1.4	-	mJ
Turn-off switching loss		E _{off}	-	2.0	-	
Total switching loss	1	E _{ts}	-	3.4	_	

^{*}Includes diode reverse recovery loss using NGTB50N60FWG.

TYPICAL CHARACTERISTICS



V_{CE}, COLLECTOR-EMITTER VOLTAGE (V) Figure 6. Typical Capacitance

T_J, JUNCTION TEMPERATURE (°C)

Figure 5. V_{CE(sat)} vs. T_J

TYPICAL CHARACTERISTICS

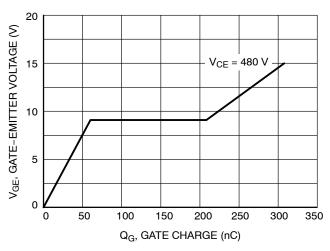


Figure 7. Typical Gate Charge

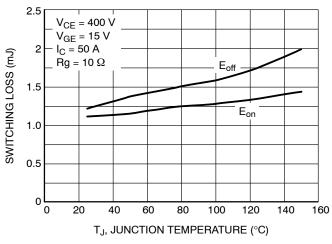


Figure 8. Switching Loss vs. Temperature

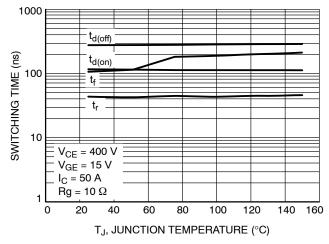


Figure 9. Switching Time vs. Temperature

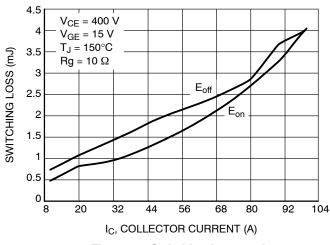


Figure 10. Switching Loss vs. I_C

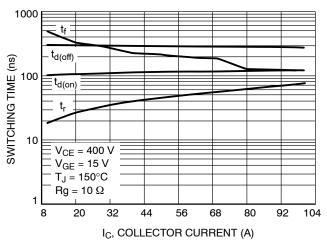
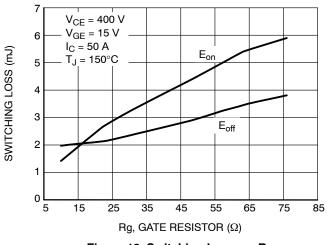


Figure 11. Switching Time vs. I_C

TYPICAL CHARACTERISTICS

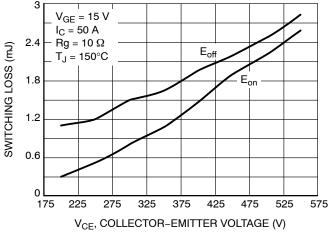
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Figure 12. Switching Loss vs. Rg

Figure 13. Switching Time vs. Rg



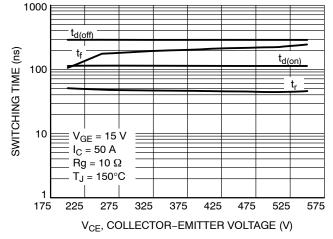
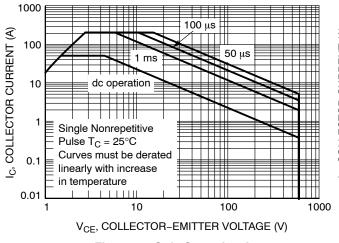


Figure 14. Switching Loss vs. V_{CE}

Figure 15. Switching Time vs. V_{CE}



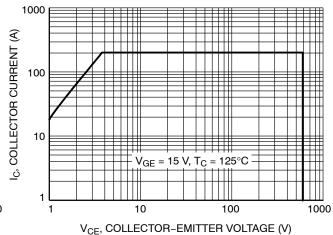


Figure 16. Safe Operating Area

Figure 17. Reverse Bias Safe Operating Area

TYPICAL CHARACTERISTICS

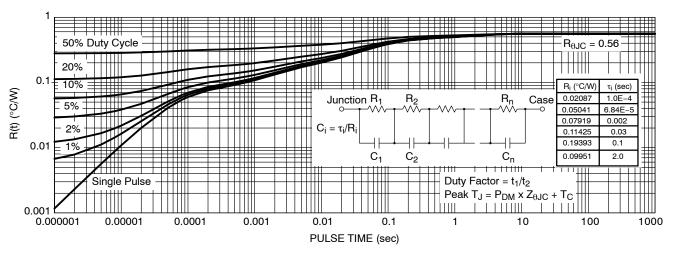


Figure 18. IGBT Transient Thermal Impedance

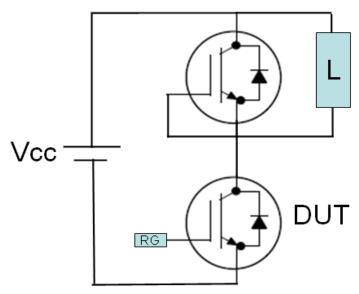


Figure 19. Test Circuit for Switching Characteristics

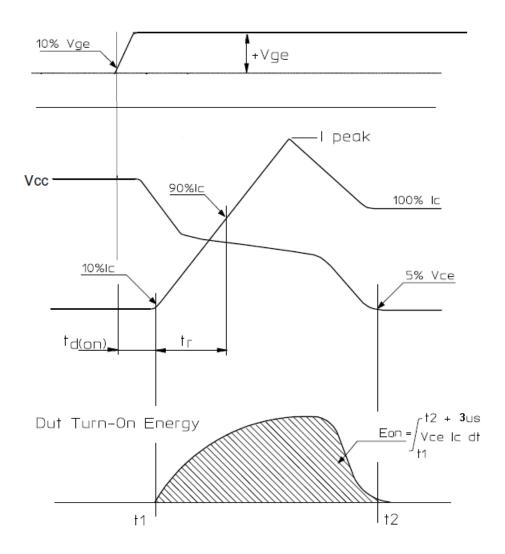


Figure 20. Definition of Turn On Waveform

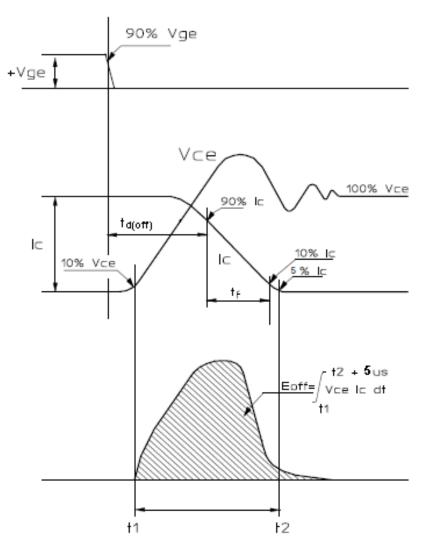
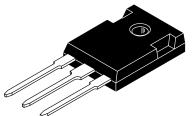


Figure 21. Definition of Turn Off Waveform





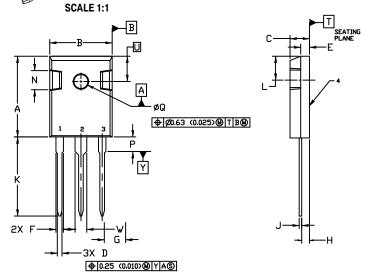
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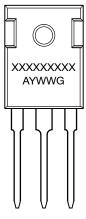
NOTES

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER

	MILLIMETERS		INC	HES
DIM	MIN.	MAX.	MIN.	MAX.
Α	20.32	21.08	0.800	0.830
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Ε	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45 BSC		0.215 BSC	
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
К	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Р		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123



GENERIC MARKING DIAGRAM*



STYLE 1:	
PIN 1.	GATE
2.	DRAIN
3.	SOURCE
4.	DRAIN

STYLE 2:
PIN 1. ANODE
2. CATHODE (S)
3. ANODE 2
4. CATHODES (S)

STYLE 3:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR

XXXXX = Specific Device Code A = Assembly Location

Y = Year
WW = Work Week
G = Pb-Free Package

 STYLE 5:
 STYLE 6:

 PIN 1. CATHODE
 PIN 1. MAIN TERMINAL 1

 2. ANODE
 2. MAIN TERMINAL 2

 3. GATE
 3. GATE

 4. ANODE
 4. MAIN TERMINAL 2

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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